

Application No.: 10/055,560

Docket No.: JCLA8532-R

In The Claims:

Claims 1-241. (canceled)

242. (new) A chip packaging method comprising:

joining a die and a substrate;

after said joining said die and said substrate, depositing a passive device over said substrate; and

separating said substrate.

243. (new) A chip packaging method comprising:

joining a die and a substrate, said die having a top surface at a horizontal level;

after said joining said die and said substrate, depositing a passive device over said horizontal level; and

separating said substrate.

244. (new) A chip packaging method comprising:

providing a die having a top surface at a horizontal level;

depositing a passive device over said horizontal level; and

depositing a trace over said horizontal level and extends to a place under which said die does not exist.